

## SCMM2512S1 Series, Current Sensor Resistor (Lead / Halogen Free)

### Features / Applications :

- Welding construction; excellent long-term stability
- Industrial applications & Current Sensor Resistor
- Ideal for all types of current sensing, voltage division and pulse applications
- RoHS compliant



### **Electrical Specifications:**

Characteristics <sup>1</sup>	Feature	
Power Rating <sup>2</sup>	1 W	
Resistance Value	0.3 to 20 m $\Omega$	
Temperature Coefficient of Resistance (25/125°C)	From 50 ppm/°C	
Operation Temperature Range	-65°C∼ +170°C	
Resistance Tolerance	± 1%	
Maximum Working Voltage (V)	( P*R) <sup>1/2</sup>	

- 1. For detail information refer to the table on page 3 P/N list
- 2. For resistors are operated at ambient temperature in excess of 70°C, the maximum load shall be derated in accordance with the following curve.

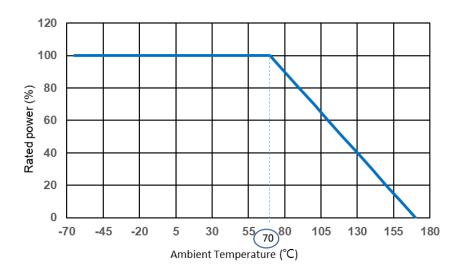


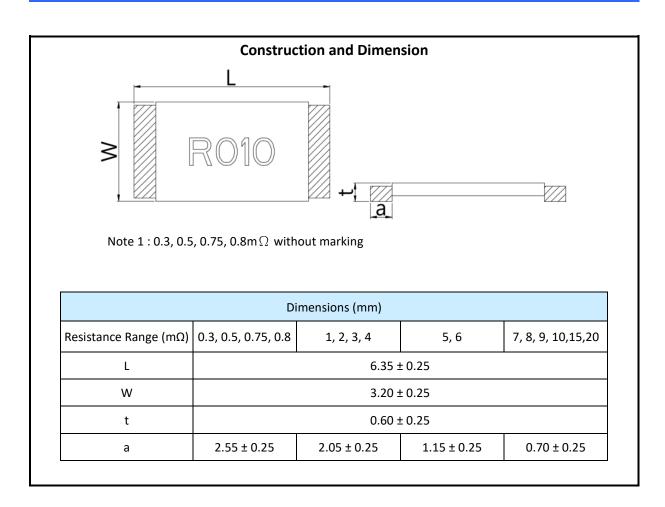
Figure 1. : Power derating curve at ambient temperature

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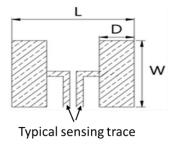
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### Outline Drawing:



#### Recommended PCB Pin Hole Dimensions



Resistance Range	Dimensions		
mΩ	W (mm)	D (mm)	L (mm)
0.3 to 4		3.2	
5 to 6	3.7	2.1	7.35
7 to 10		1.65	

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## Type Designation:

S C M M 2512 S 1 — — — —

(1) (2) (3) (4) (5) (6)

Note:

(1) Series No.

(2) Size

(3) Terminal Type : S = Short terminal

(4) Power Rating: 1 = 1W

(5) Resistance value :  $R003 = 0.003\Omega$ ,  $OM50 = 0.0005\Omega$ 

(6) Tolerance :  $F = \pm 1\%$ ,  $G = \pm 2\%$ ,  $J = \pm 5\%$ 

# P/N list:

P/N	R value	TCR	Power Rating	Tolerance		
P/N	(mΩ)	(ppm/K)	(W)	1%	2%	5%
SCMM2512S1-0M30*	0.3	±100	1	✓		
SCMM2512S1-0M50*	0.5	±75	1	✓		
SCMM2512S1-0M75*	0.75	±75	1	<b>√</b>		
SCMM2512S1-0M80*	0.8	±75	1	<b>√</b>		
SCMM2512S1-R001*	1.0	±50	1	<b>√</b>		
SCMM2512S1-R002*	2.0	±50	1	✓		
SCMM2512S1-R003*	3.0	±50	1	<b>√</b>		
SCMM2512S1-R004*	4.0	±50	1	✓		
SCMM2512S1-R005*	5.0	±50	1	<b>√</b>		
SCMM2512S1-R006*	6.0	±50	1	✓		
SCMM2512S1-R007*	7.0	±50	1	✓		
SCMM2512S1-R008*	8.0	±50	1	<b>√</b>		
SCMM2512S1-R009*	9.0	±50	1	✓		
SCMM2512S1-R010*	10.0	±50	1	✓		
SCMM2512S1-R015*	15.0	±50	1	✓		
SCMM2512S1-R020*	20.0	±50	1	✓		

<sup>\*</sup> Note : Other values and tolerance would be available, please contact Cyntec.

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## Characteristics:

### Electrical

Item	Specification and Requirement	Test Method
Temperature Coefficient (TCR)	As follow specification	JIS-C-5201 +25°C/ +125°C.
Short Time Overload	$\triangle R$ : $\pm$ 0.5% Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.13 2.5 x rated power for 5 seconds.
ESD	$\triangle R$ : $\pm$ 1% Without damage by flashover, spark, arcing, burning or breakdown	AEC-Q200-002 Human body, 8KV.
Insulation Resistance	Over 100 M $\Omega$ on Overcoat layer face up	JIS-C-5201-1 4.6 100V <sub>DC</sub> for 60 +10/-0 seconds
Voltage Proof	$\triangle$ R: $\pm$ 1% Without damage by flashover, spark, arcing, burning or breakdown	JIS-C-5201-1 4.7 400V <sub>AC</sub> (rms.) for 60 +10/ -0 seconds

#### Mechanical

Item	Specification and Requirement	Test Method
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	J-STD-002 Method B category 3 245±5°C for 5±0.5 seconds.
Resistance to Solder Heat	$\triangle$ R: $\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 210 $260 \pm 5 ^{\circ}\text{C} \ \text{ for } 10 \pm 1 \text{ seconds}.$
Board Flex	$\triangle$ R: $\pm$ 1.0% Without mechanical damage such as break.	AEC-Q200-005  Bending value: 2 mm for 60 ± 1 seconds.

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Vibration		MIL-STD-202 Method 204	
	△R: ± 0.5%	5G's for 20 minutes, 12 cycles each	
Vibration	Without distinct damage in appearance	of 3 orientations. Test from 10-	
		2000Hz.	
		MIL-STD-202 Method 213	
Mechanical Shock	$\triangle$ R: $\pm$ 0.5% Without distinct damage in appearance	100G's peak value, 6ms,	
		Half-sine waveform, 12.3ft/sec.	
Terminal Strength	△R: ± 1%	AEC-Q200-006	
(SMD)	Without mechanical damage such as break.	Force of 1.8Kg for 60 seconds.	

#### **Endurance**

Item	Specification and Requirement	Test Method
Temperature Cycling	$\triangle$ R: $\pm$ 0.5% Without distinct damage in appearance	JESD22 Method JA-104 -55°C to 150°C /1000cycle 30 min maximum dwell time at each temperature.
Biased Humidity	$\triangle R$ : $\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 103 1000 hours, 85°C/85%R.H, applied for 10% rated power.
Operational Life	$\triangle$ R: $\pm$ 1.0% Without distinct damage in appearance	MIL-STD-202 Method 108 70°C, 100% rated power 1.5 hours ON, 0.5 hours Off For total 1000 hours
High Temperature Storage	$\triangle$ R: $\pm$ 1.0% Without distinct damage in appearance	MIL-STD-202 Method 108 170°C for 1000 hours.
Moisture Resistance	$\triangle R$ : $\pm$ 0.5% Without distinct damage in appearance	MIL-STD-202 Method 106 65°C /90-100%RH, unpowered, 7b not required

Note : Measurement at 24 $\pm$ 4 hours after test conclusion for all reliability tests-parts.

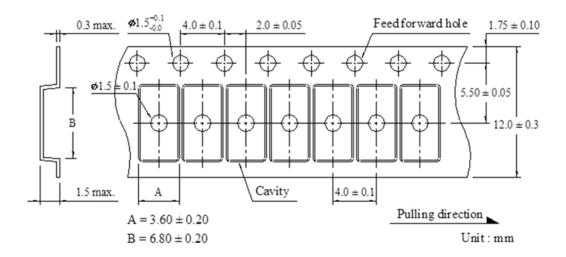
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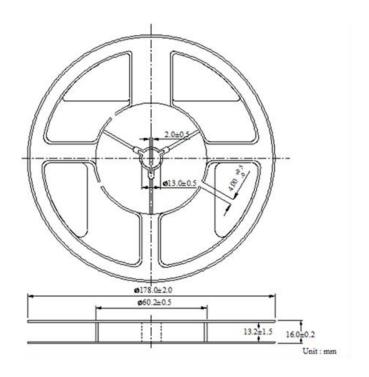


### PACKAGING DESCRIPTIONS:

#### Dimensions:



#### Reel Dimensions:



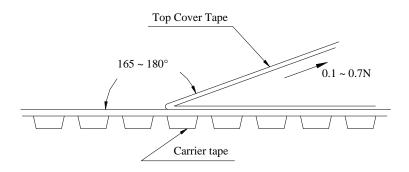
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#### Peel Strength of Top Cover Tape:

The peel speed shall be about 300mm/min and the peel force of top cover tape shall between 0.1 to 0.7N



### Number of Taping:

2,000 pieces / reel

#### Label Marking:

The following items shall be marked on tray

- (1) Description
- (2) Quantity
- (3) Part No.
- (4) Tapping No.

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#### Care Note:

#### Care note for storage

- (1) Chip resistor shall be stored in a room where temperature and humidity must be controlled. (temperature 5 to 35°C, humidity < 60% RH) However, a humidity keep it low, as it is possible.
- (3) Chip resistor shall be stored as direct sunshine doesn't hit on it.
- (4) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (Chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen)

#### Care note for operating and handling

- (1) Protect the edge and coating of the sensors from mechanical stress.
- (2) Avoid bending of printing circuit board (PCB) when cutting and fixing it on support body to reduce mechanical stress on sensors.
- (3) Sensor should be used within the condition of specification.
  Note: When a voltage higher than specified value is loaded to the sensor, this may damage the sensor material due to temperature rise.
- (4) The loaded voltage should consult terminal temperature of the sensor according to the derating curve.
- (5) When applying a high current exceeding suggested specification (pulse current, shock current) to the sensor, it is necessary to re-evaluate the operating condition before using it in the system.

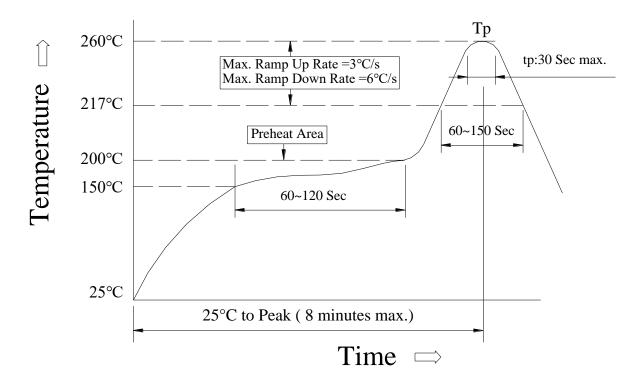
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## Reflow profile:

#### Recommended Reflow Profile



#### (1) Reflow Soldering Method:

Reflow Soldering	Tp:255~260°C	Max.30 seconds ( tp )
	217°C	60~150 seconds
Pre-Heat	150 ~ 200°C	60~120 seconds
Time 25°C to peak temperature	8 minutes max.	

Reference: JEDEC J-STD-020D

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